



GE Energy

Functional Testing Specification

*Parts & Repair Services
Louisville, KY*

LOU-GENEVA-IS200EDCFG1A

Functional test procedure for a card tested on the GENEVA system

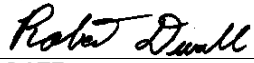
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REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	R. Duvall	05/21/03
B	Identified test fixture number and card specific test.	F. Howard	11/09/2010
C			

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PREPARED BY Robert Duvall	REVIEWED BY Frank Howard	REVIEWED BY	QUALITY APPROVAL 
DATE 05/21/03	DATE 11/9/2010	DATE	DATE 05/21/03

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Functional test procedure for equipment tested on the GENRAD® GENEVA system

1. SCOPE

1.1 This is a functional testing procedure for various circuit boards.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check the board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires broken or cracked

4.2.1.2 Terminal strips / connectors broken or cracked

4.2.1.3 Loose wires

4.2.1.4 Components visually damaged

4.2.1.5 Capacitors leaking

4.2.1.6 Solder joints damaged or cold

4.2.1.7 Circuit board burned or de-laminated

4.2.1.8 Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	H188912	GENRAD Geneva Test System
1	H188751	EDCF #G36 Test Fixture

6. TESTING PROCESS

6.1 Setup

6.1.1 There are two programs for the EDCF card. Be sure to pull up the correct program.

6.1.2 Install fixture H188751 onto Geneva test System.

6.1.3 Install UUT into test fixture.

6.2 Testing Procedure

6.2.1 Load appropriate test program and follow instructions on screen.

6.3 ***TEST COMPLETE ***

7. Notes

7.1 Changes to the electronic test file are located in the following directory on the local hard drive; C:\GenevaInfo\Geneva\Geneva Test Fixture Notes.

7.1.1 These changes have been backed up on CD.

8. Attachments

8.1 Picture of the Geneva Test System



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